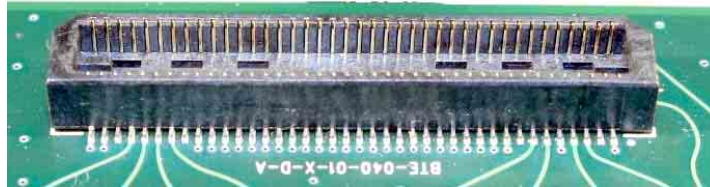


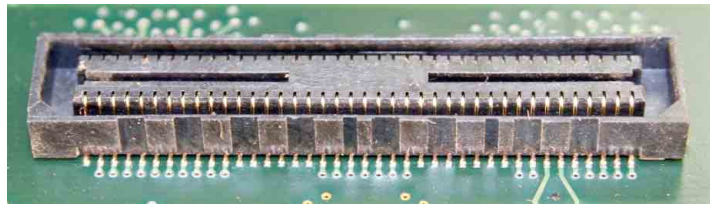


High Speed Characterization Report

BTE-040-01-F-D-A



Mated With



BSE-040-01-L-D-A

Description:

Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Table of Contents

Connector Overview	1
Connector System Speed Rating	1
Frequency Domain Data Summary	2
Table 1 - Single-Ended Connector System Performance	2
Table 2 - Differential Connector System Bandwidth	2
Time Domain Data Summary	3
Table 3 - Single-Ended Impedance (Ω)	3
Table 4 - Differential Impedance (Ω)	3
Table 5 - Single-Ended Crosstalk (%)	4
Table 6 - Differential Crosstalk (%)	4
Table 7 - Propagation Delay (Mated Connector)	4
Characterization Details	5
Differential and Single-Ended Data	5
Connector Signal to Ground Ratio	5
Frequency Domain Data	7
Time Domain Data	7
Appendix A – Frequency Domain Response Graphs	9
Single-Ended Application – Insertion Loss	9
Single-Ended Application – Return Loss	9
Single-Ended Application – NEXT	10
Single-Ended Application – FEXT	10
Differential Application – Insertion Loss	11
Differential Application – Return Loss	11
Differential Application – NEXT	12
Differential Application – FEXT	12
Appendix B – Time Domain Response Graphs	13
Single-Ended Application – Input Pulse	13
Single-Ended Application – Impedance	14
Single-Ended Application – Propagation Delay	14
Single-Ended Application – NEXT, “Worst Case” Configuration	15
Single-Ended Application – FEXT, “Worst Case” Configuration	15
Single-Ended Application – NEXT, “Best Case” Configuration	16
Single-Ended Application – FEXT, “Best Case” Configuration	16
Single-Ended Application – NEXT, Across Row	17
Single-Ended Application – FEXT, Across Row	17
Differential Application – Input Pulse	18
Differential Application – Impedance	19
Differential Application – Propagation Delay	19
Differential Application – NEXT, “Worst Case” Configuration	20
Differential Application – FEXT, “Worst Case” Configuration	20

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197”) Stack Height

Differential Application – NEXT, “Best Case” Configuration	21
Differential Application – FEXT, “Best Case” Configuration	21
Differential Application – NEXT, Across Row	22
Differential Application – FEXT, Across Row	22
Appendix C – Product and Test System Descriptions	23
Product Description	23
Test System Description	23
Table 8 – PCB Fixture Characterization Setup	24
Appendix D – Test and Measurement Setup	25
Test Instruments	26
Measurement Station Accessories	26
Test Cables & Adapters	26
Appendix E - Frequency and Time Domain Measurements	27
Frequency (S-Parameter) Domain Procedures	27
CSA8000 Setup	27
Insertion Loss	28
Return Loss	28
Near-End Crosstalk (NEXT)	29
Far-End Crosstalk (FEXT)	29
Time Domain Procedures	30
Impedance	30
Propagation Delay	30
Crosstalk	30
Appendix F – Glossary of Terms	31

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Connector Overview

BSE/BTE Series.8mm (.0315") pitch interfaces are available with up to 120 contacts per row and with standard board-to-board spacing of 5mm (0.197"), 8mm (0.315"), 11mm (0.433"), and 16mm (0.630") between boards. The data in this report is applicable only to the 5mm (0.197") board-to-board stack height version.

Connector System Speed Rating

BSE/BTE Series, Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197")Stack Height

<u>Signaling</u>	<u>Speed Rating</u>
Single-Ended:	8 GHz / 16 Gbps
Differential:	5 GHz / 10 Gbps

The Speed Rating is based on the -3 dB insertion loss point of the connector system. The -3 dB point can be used to estimate usable system bandwidth in a typical, two-level signaling environment.

To calculate the Speed Rating, the measured -3 dB point is rounded up to the nearest half-GHz level. The up-rounding corrects for a portion of the test board's trace loss, since trace losses are included in the loss data in this report. The resulting loss value is then doubled to determine the approximate maximum data rate in Gigabits per second (Gbps).

For example, a connector with a -3 dB point of 7.8 GHz would have a Speed Rating of 8 GHz/ 16 Gbps. A connector with a -3 dB point of 7.2 GHz would have a Speed Rating of 7.5 GHz/ 15 Gbps.

Series: BSE/BTE

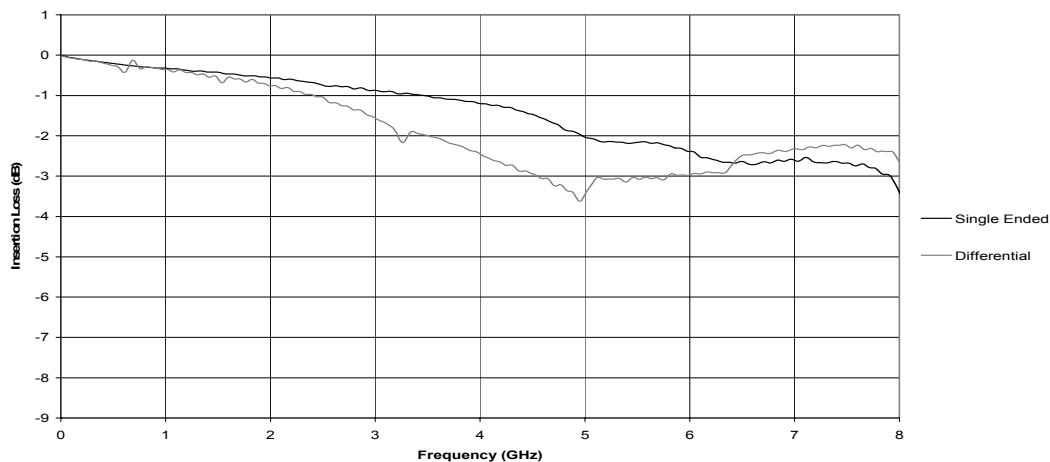
Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Frequency Domain Data Summary

Table 1 - Single-Ended Connector System Performance		
Test Parameter	Configuration	
Insertion Loss	GSG	-3dB @ 7.92GHz
Return Loss	GSG	< -5dB to 7.92GHz
Near-End Crosstalk	GAQG	< -8dB to 7.92GHz
	GAGQG	< -18dB to 7.92GHz
	Xrow, GAG to GQG	< -28dB to 7.92GHz
Far-End Crosstalk	GAQG	< -12dB to 7.92GHz
	GAGQG	< -18dB to 7.92GHz
	Xrow, GAG to GQG	< -30dB to 7.92GHz

Table 2 - Differential Connector System Bandwidth		
Test Parameter	Configuration	
Insertion Loss	GSSG	-3dB @ 4.56 GHz
Return Loss	GSSG	< -5dB to 4.56 GHz
Near-End Crosstalk	GAAQQG	< -15dB to 4.56 GHz
	GAAGQQG	< -32dB to 4.56 GHz
	Xrow, GAAG to GQQG	< -40dB to 4.56 GHz
Far-End Crosstalk	GAAQQG	< -15dB to 4.56 GHz
	GAAGQQG	< -30dB to 4.56 GHz
	Xrow, GAAG to GQQG	< -40dB to 4.56 GHz

**PCB/Connector Test System
Single Ended & Differential Signal Response
BSE-01 / BTE-01**



Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Time Domain Data Summary

Table 3 - Single-Ended Impedance (Ω)							
Signal Risetime	30 \pm 5ps	50 ps	100 ps	250 ps	500 ps	750 ps	1 ns
Maximum Impedance	65.4	59.6	55.0	52.4	52.1	51.9	51.7
Minimum Impedance	41.1	44.9	46.9	50.1	50.5	50.6	50.6

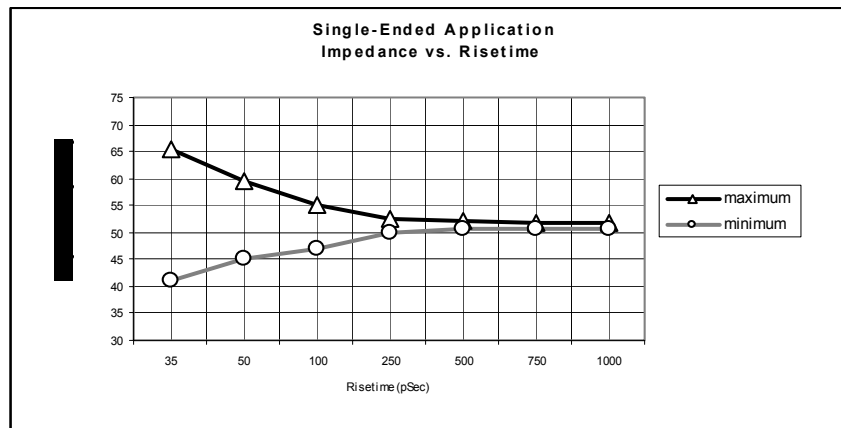
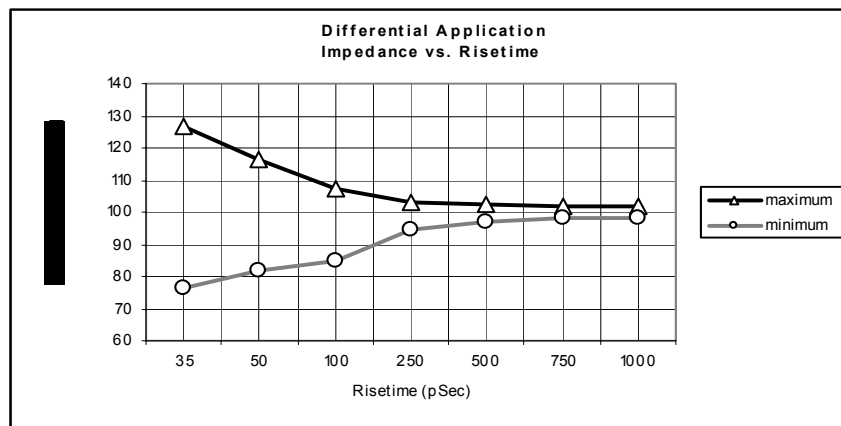


Table 4 - Differential Impedance (Ω)							
Signal Risetime	30 \pm 5ps	50 ps	100 ps	250 ps	500 ps	750 ps	1 ns
Maximum Impedance	126.8	116.7	107.1	103.0	102.3	101.8	101.5
Minimum Impedance	76.4	82.0	84.9	94.7	97.2	98.0	98.2



Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Table 5 - Single-Ended Crosstalk (%)								
Input (t _r)		30±5ps	50 ps	100 ps	250 ps	500 ps	750 ps	1 ns
NEXT	GAQG	14.6	13.1	10.8	6.1	3.5	2.5	1.9
	GAGQG	3.3	2.8	2.2	1.2	< 1.0	< 1.0	< 1.0
	Xrow ^{se}	< 1.0	< 1.0	< 1.0	< 1.0	< 1.0	< 1.0	< 1.0
FEXT	GAQG	5.8	4.4	3.0	1.4	0.5	0.4	0.3
	GAGQG	4.0	2.9	1.8	< 1.0	< 1.0	< 1.0	< 1.0
	Xrow ^{se}	1.2	< 1.0	< 1.0	< 1.0	< 1.0	< 1.0	< 1.0

Table 6 - Differential Crosstalk (%)								
Input (t _r)		30±5ps	50 ps	100 ps	250 ps	500 ps	750 ps	1 ns
NEXT	GAAQQG	4.9	4.2	3.7	2.0	1.0	< 1.0	< 1.0
	GAAGQQG	1.3	1.0	< 1.0	< 1.0	< 1.0	< 1.0	< 1.0
	Xrow ^{diff}	< 1.0	< 1.0	< 1.0	< 1.0	< 1.0	< 1.0	< 1.0
FEXT	GAAQQG	2.8	2.6	2.2	1.0	< 1.0	< 1.0	< 1.0
	GAAGQQG	1.3	1.0	< 1.0	< 1.0	< 1.0	< 1.0	< 1.0
	Xrow ^{diff}	< 1.0	< 1.0	< 1.0	< 1.0	< 1.0	< 1.0	< 1.0

Table 7 - Propagation Delay (Mated Connector)	
Single-Ended	84.0 ps
Differential	81.0 ps

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Characterization Details

This report presents data which characterizes the signal integrity response of a connector pair in a controlled printed circuit board (PCB) environment. All efforts are made to reveal typical best-case responses inherent to the system under test (SUT).

In this report, the SUT includes the test PCB from drive side probe tips to receive side probe tips. PCB effects are not removed or de-embedded from the test data. PCB designs with impedance mismatch, large losses, skew, cross talk, or similar impairments can have a significant impact on observed test data. Therefore, great design effort is put forth to limit these effects in the PCB utilized in these tests. Some board related effects, such as pad-to-ground capacitance and trace loss, are included in the data presented in this report. But other effects, such as via coupling or stub resonance, are not evaluated here. Such effects are addressed and characterized fully by the Samtec [Final Inch®](#) products.

Additionally, intermediate test signal connections can mask the connectors' true performance. Such connection effects are minimized by using high performance test cables, adapters, and microwave probes. Where appropriate, calibration and de-embedding routines are also used to reduce residual effects.

Differential and Single-Ended Data

Most Samtec connectors can be used successfully in both differential and single-ended applications. However, electrical performance will differ depending on the signal drive type. In this report, data is presented for both differential and single-ended drive scenarios.

Connector Signal to Ground Ratio

Samtec connectors are most often designed for generic applications, and can be implemented using various signal and ground pin assignments. In high speed systems, provisions must be made in the interconnect for signal return currents. Such paths are often referred to as "ground". In some connectors, a ground plane or blade, or an outer shield is used as the signal return, while in others, connector pins are used as signal returns. Various combinations of signal pins, ground blades, and shields can also be utilized. Electrical performance can vary significantly depending upon the number and location of ground pins.

In general, the more pins dedicated to ground, the better electrical performance will be. But dedicating pins to ground reduces signal density of a connector. So care must be taken when choosing signal/ground ratios in cost- or density-sensitive applications.

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

For this connector, the following configurations were evaluated:

Single-Ended Impedance:

- GSG (ground-signal-ground)

Single-Ended Crosstalk:

- Electrical "worst case": GAQG (ground-active-quiet-ground)
- Electrical "best case": GAGQG (ground-active-ground-quiet-ground)
- Across row: X_{row}^{se} (from one row of terminals to the other row across the ground blade)

Differential Impedance:

- GSSG (Ground-positive signal-negative signal-ground)

Differential Crosstalk:

- Electrical "worst case": GAAQQG (ground-active-active-quiet-quiet-ground)
- Electrical "best case": GAAGQQG (ground-active-active-ground-quiet-quiet-ground)
- Across row: X_{row}^{diff} (from one row of terminals to another row of terminals or across a ground blade)

In all cases in this report, only one single-ended signal or differential pair was driven for crosstalk measurements.

Other configurations can be evaluated upon request. Please contact sig@samtec.com for more information.

In a real system environment, active signals might be located at the outer edges of the signal contacts of concern, as opposed to the ground signals utilized in laboratory testing. For example, in a single-ended system, a pin-out of "SSSS", or four adjacent single ended signals, might be encountered, as opposed to the "GSG" and "GSSG" configurations tested in the laboratory. Electrical characteristics in such applications could vary slightly from laboratory results. But in most applications, performance can safely be considered equivalent.

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Signal Edge Speed (Rise Time):

In pulse signaling applications, the perceived performance of an interconnect can vary significantly depending on the edge rate or rise time of the exciting signal. For this report, the fastest rise time used was 30 +/-5 ps. Generally, this should demonstrate worst case performance.

In many systems, the signal edge rate will be significantly slower at the connector than at the driver launch point. To estimate interconnect performance at other edge rates, data is provided for several rise times between 30 ps and 1.0 ns.

For this report, rise times were measured at 10%-90% signal levels.

Frequency Domain Data

Frequency domain parameters are helpful in evaluating the connector system's signal loss and crosstalk characteristics across a range of sinusoidal frequencies. In this report, parameters presented in the frequency domain are insertion loss, return loss, and near-end and far-end crosstalk. Other parameters or formats, such as VSWR or S-parameters, may be available upon request. Please contact our Signal Integrity Group at sig@samtec.com for more information.

Frequency performance characteristics for the SUT are generated from time domain measurements using Fourier Transform calculations. Procedures and methods used in generating the SUT's frequency domain data are provided in the frequency domain test procedures in [Appendix E](#) of this report.

Time Domain Data

Time Domain parameters indicate impedance mismatch versus length, signal propagation time, and crosstalk in a pulsed signal environment. Time Domain data is provided in [Appendix E](#) of this report. Parameters or formats not included in this report may be available upon request. Please contact our Signal Integrity Group at sig@samtec.com for more information.

Reference plane impedance is 50 ohms for single-ended measurements and 100 ohms for differential measurements. The fastest risetime signal exciting the SUT is 30 ± 5 picoseconds.

In this report, propagation delay is defined as the signal propagation time through the PCB connector pads and connector pair. It does not include PCB traces. Delay is measured at 30 ± 5 picoseconds signal risetime. Delay is calculated as the difference in time measured between the 50% amplitude levels of the input and output pulses.

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Crosstalk or coupled noise data is provided for various signal configurations. All measurements are single disturber. Crosstalk is calculated as a ratio of the input line voltage to the coupled line voltage. The input line is sometimes described as the active or drive line. The coupled line is sometimes described as the quiet or victim line. Crosstalk ratio is tabulated in this report as a percentage. Measurements are made at both the near-end and far-end of the SUT.

Data for other configurations may be available. Please contact our Signal Integrity Group at sig@samtec.com for further information.

As a rule of thumb, 10% crosstalk levels are often used as a general first pass limit for determining acceptable interconnect performance. But modern system crosstalk tolerance can vary greatly. For advice on connector suitability for specific applications, please contact our Signal Integrity Group at sig@samtec.com.

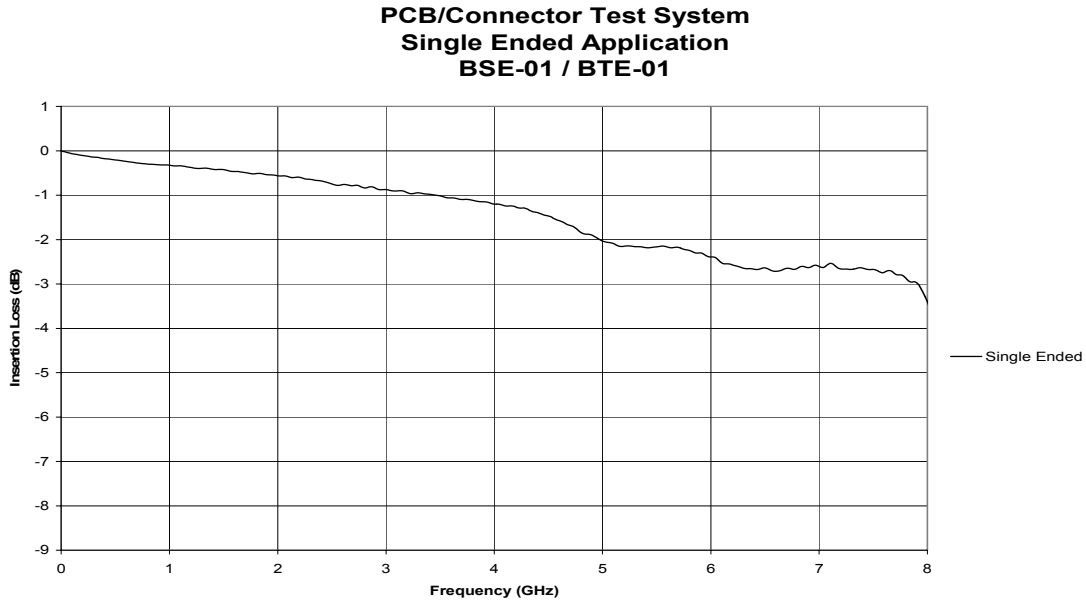
Additional information concerning test conditions and procedures is located in the appendices of this report. Further information may be obtained by contacting our Signal Integrity Group at sig@samtec.com.

Series: BSE/BTE

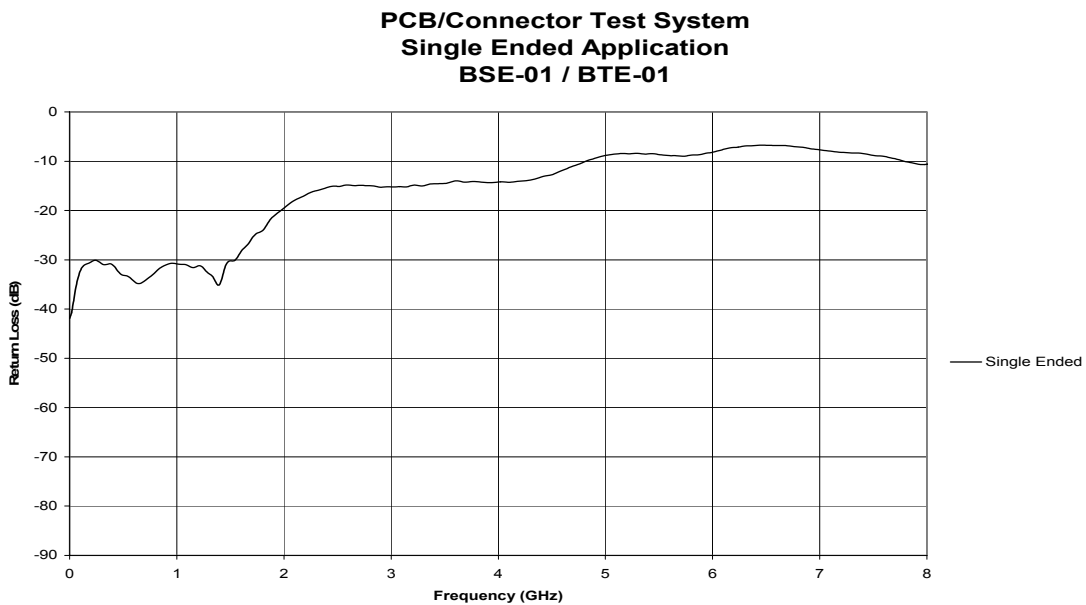
Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Appendix A – Frequency Domain Response Graphs

Single-Ended Application – Insertion Loss



Single-Ended Application – Return Loss

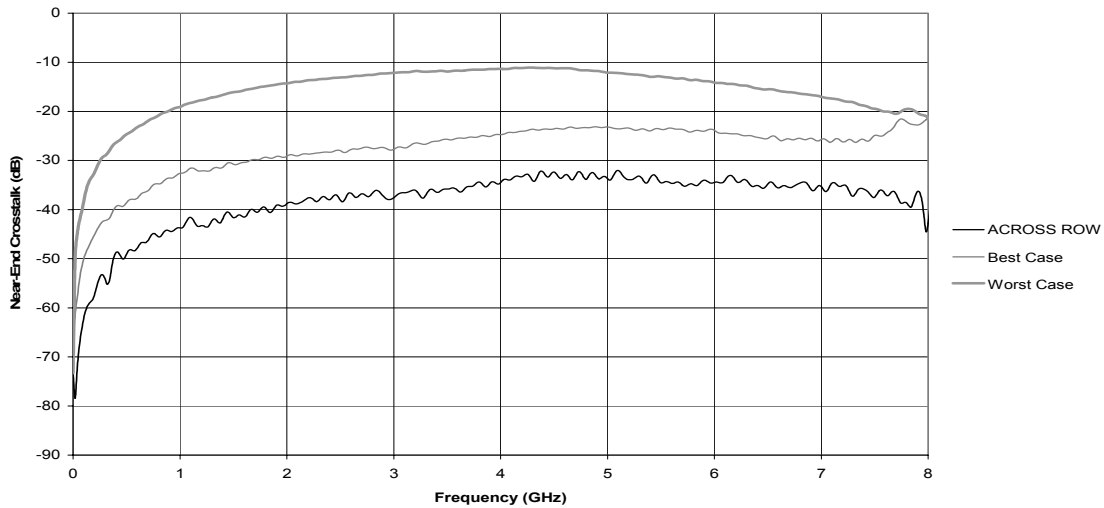


Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

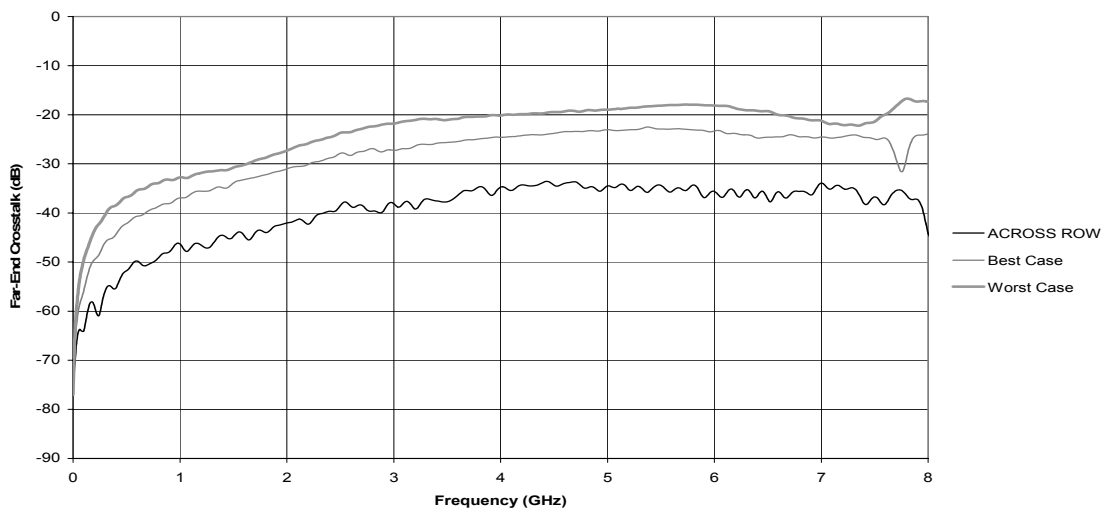
Single-Ended Application – NEXT

PCB/Connector Test System
Single Ended Application
BSE-01 / BTE-01



Single-Ended Application – FEXT

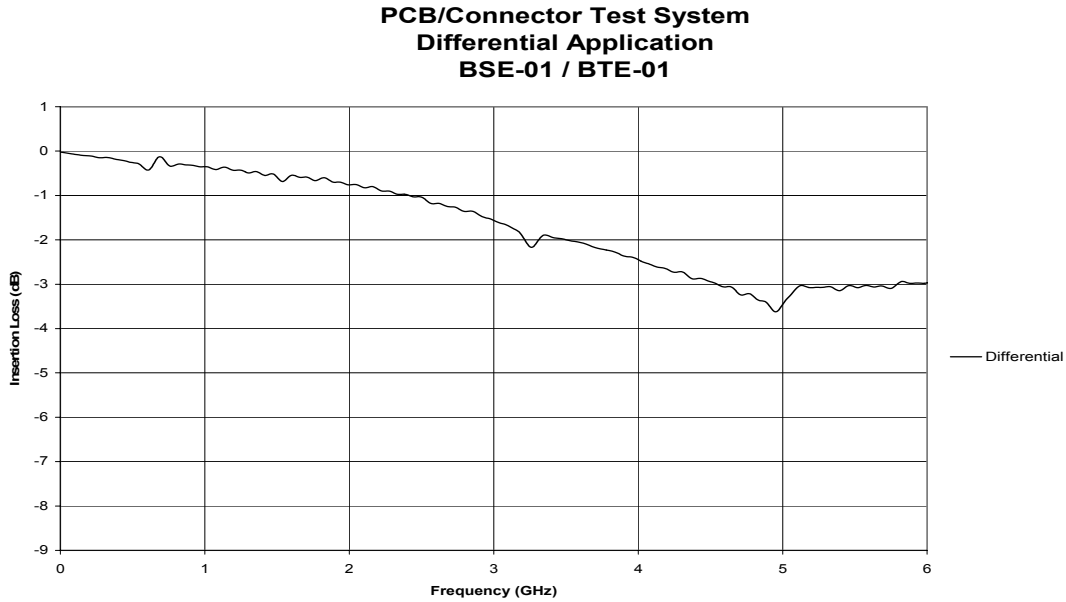
PCB/Connector Test System
Single Ended Application
BSE-01 / BTE-01



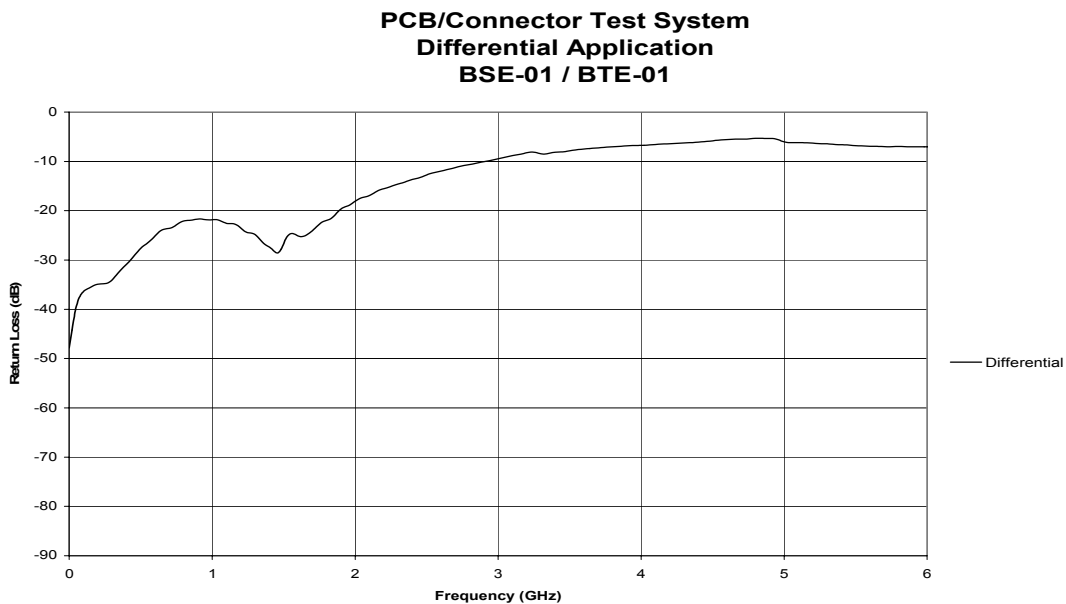
Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Differential Application – Insertion Loss



Differential Application – Return Loss

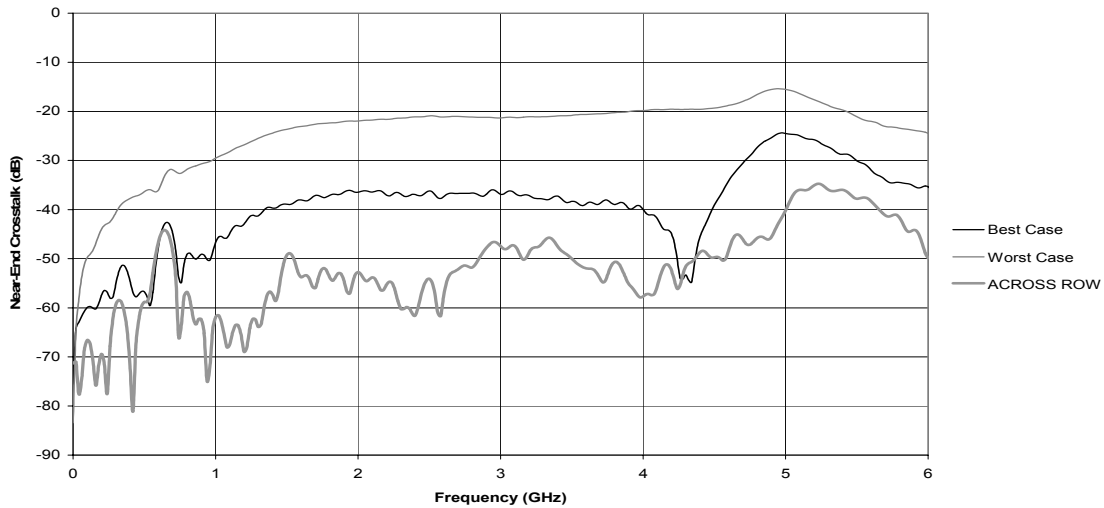


Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

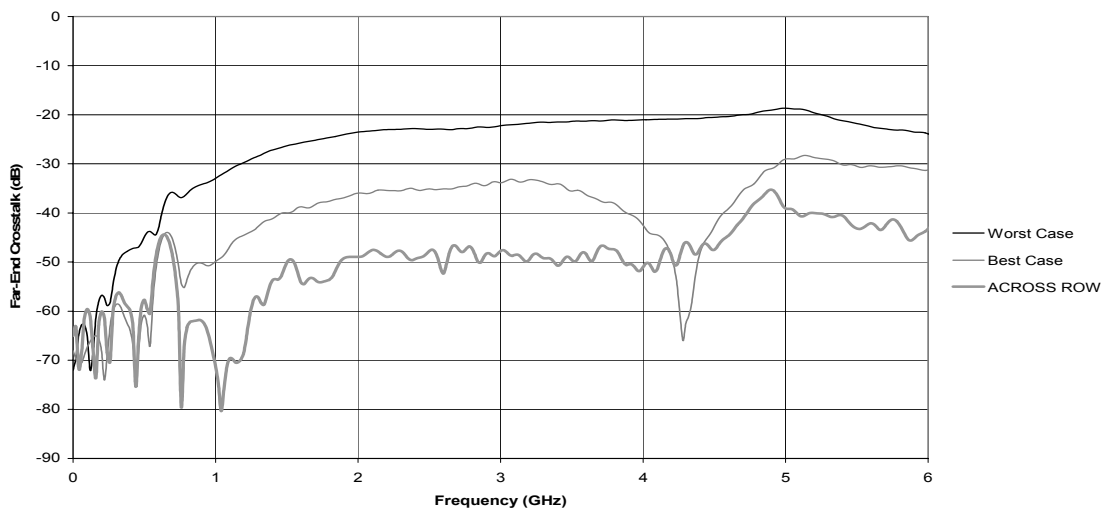
Differential Application – NEXT

PCB/Connector Test System
Differential Application
BSE-01 / BTE-01



Differential Application – FEXT

PCB/Connector Test System
Differential Application
BSE-01 / BTE-01

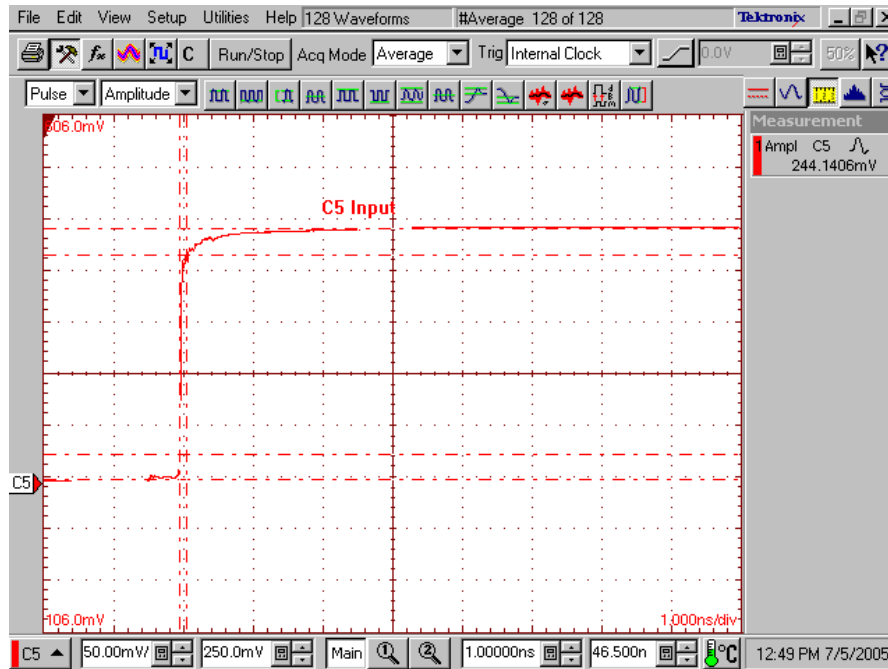


Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Appendix B – Time Domain Response Graphs

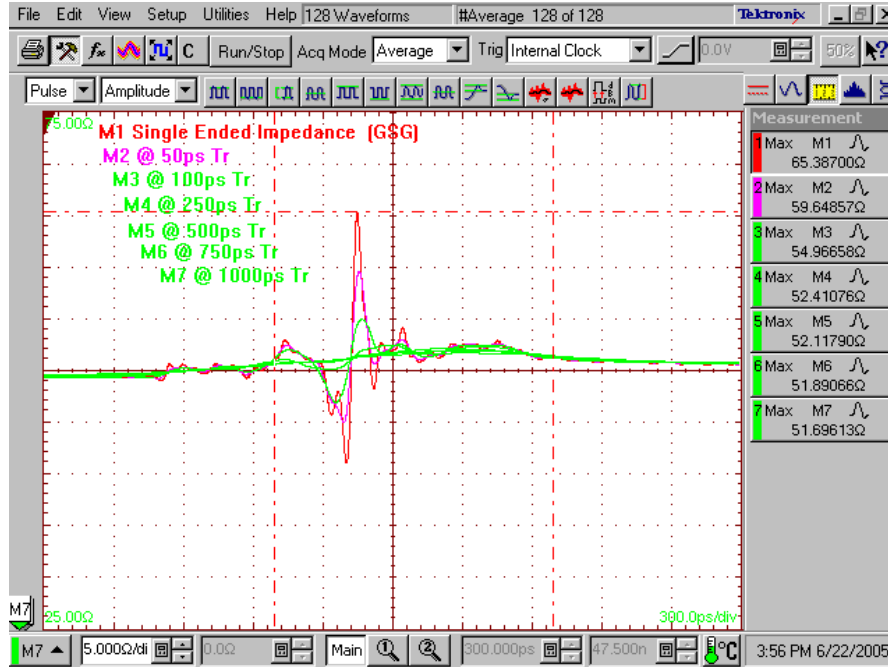
Single-Ended Application – Input Pulse



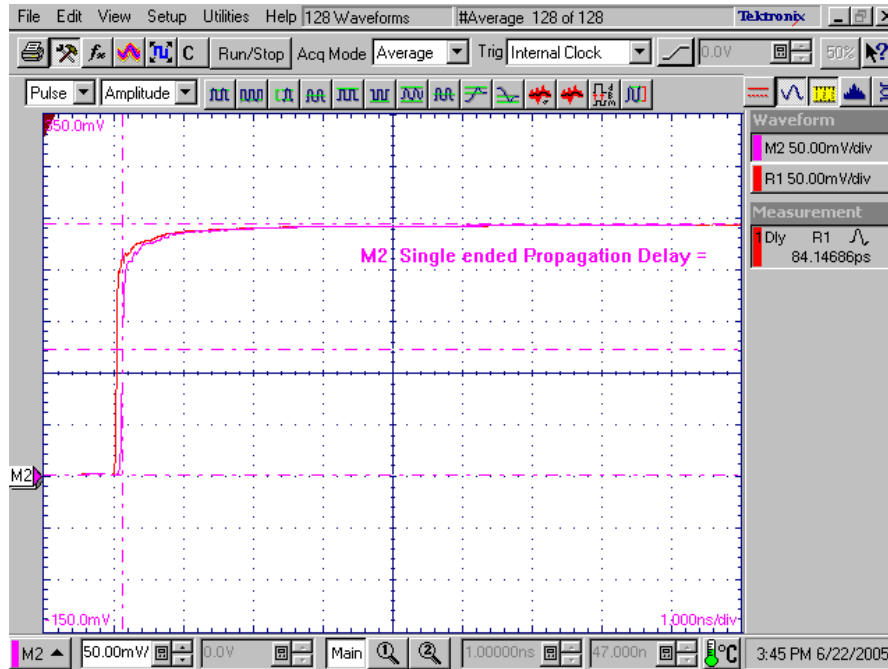
Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Single-Ended Application – Impedance



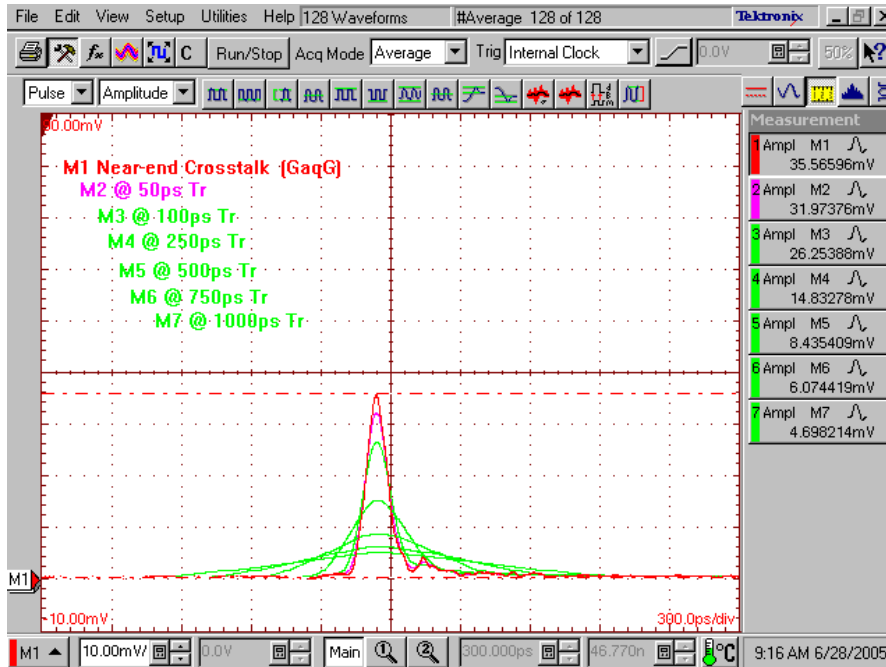
Single-Ended Application – Propagation Delay



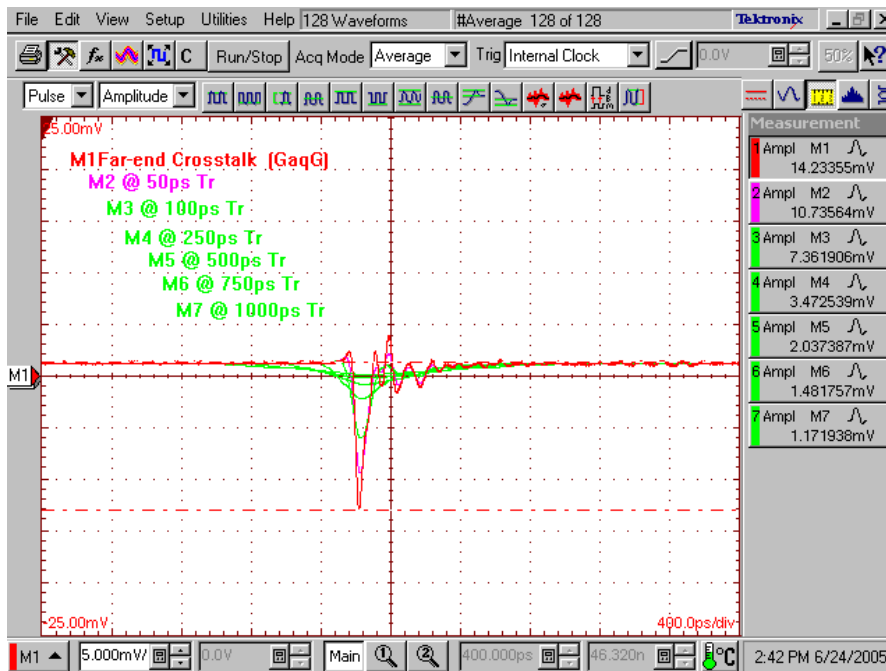
Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Single-Ended Application – NEXT, “Worst Case” Configuration



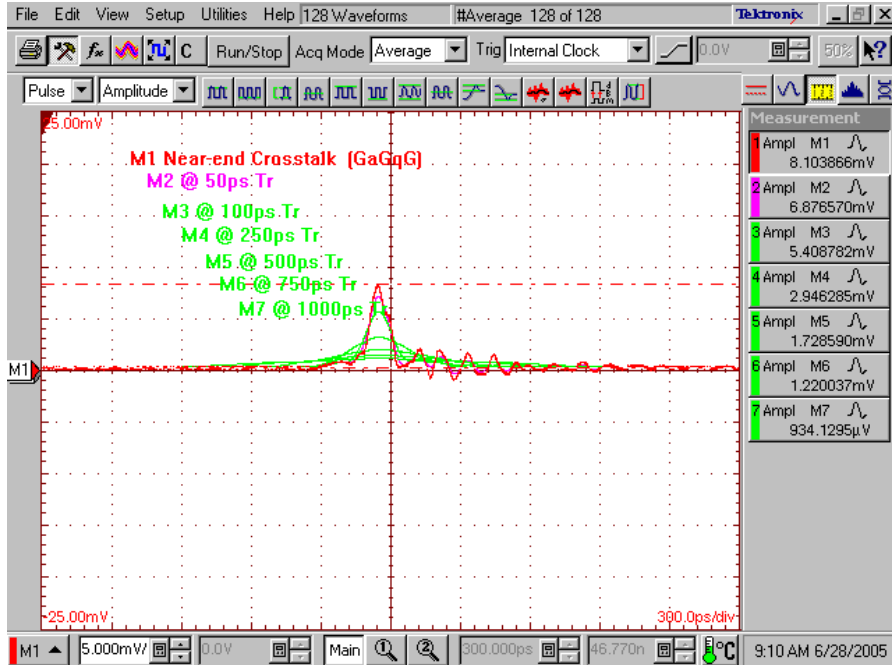
Single-Ended Application – FEXT, “Worst Case” Configuration



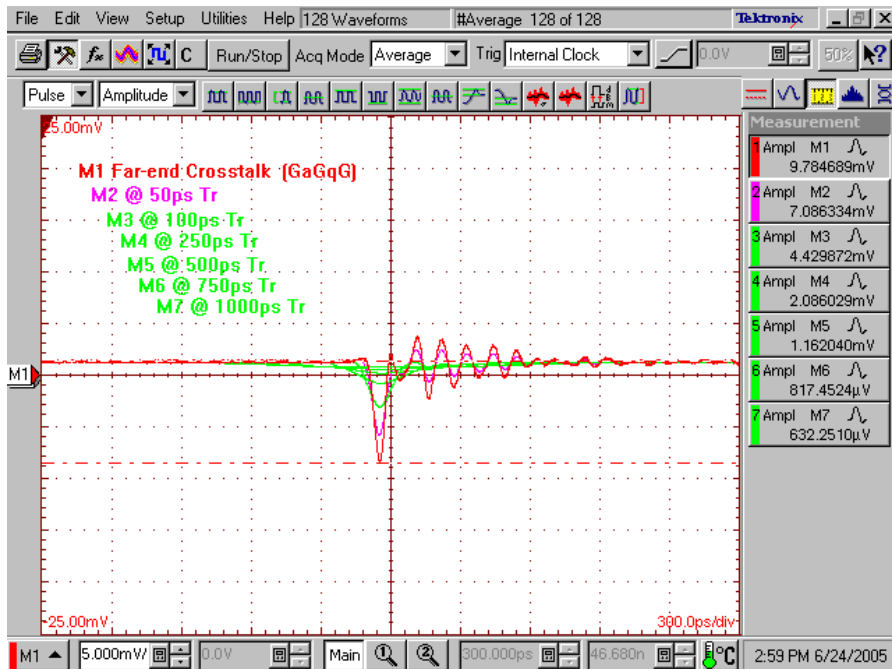
Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Single-Ended Application – NEXT, “Best Case” Configuration



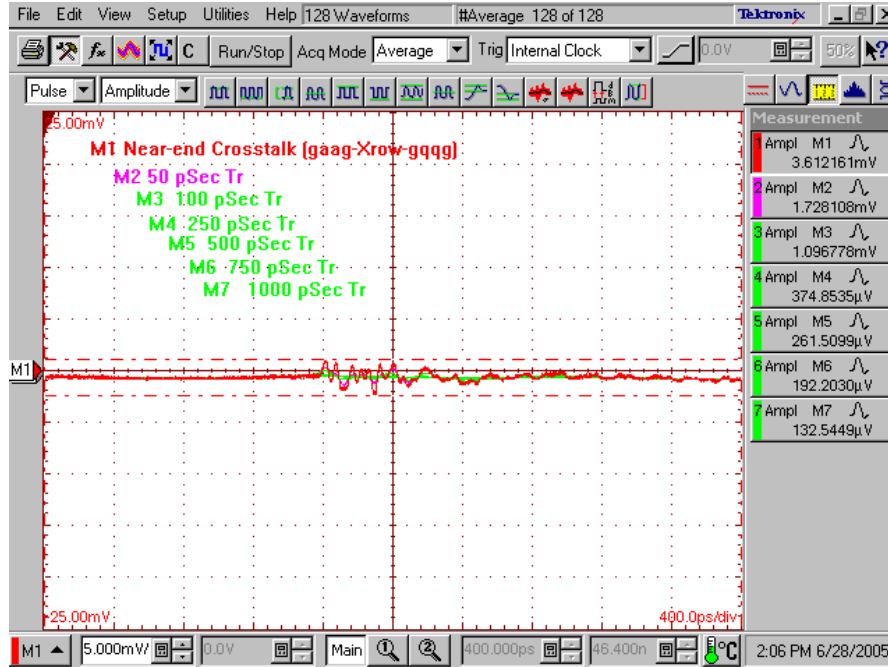
Single-Ended Application – FEXT, “Best Case” Configuration



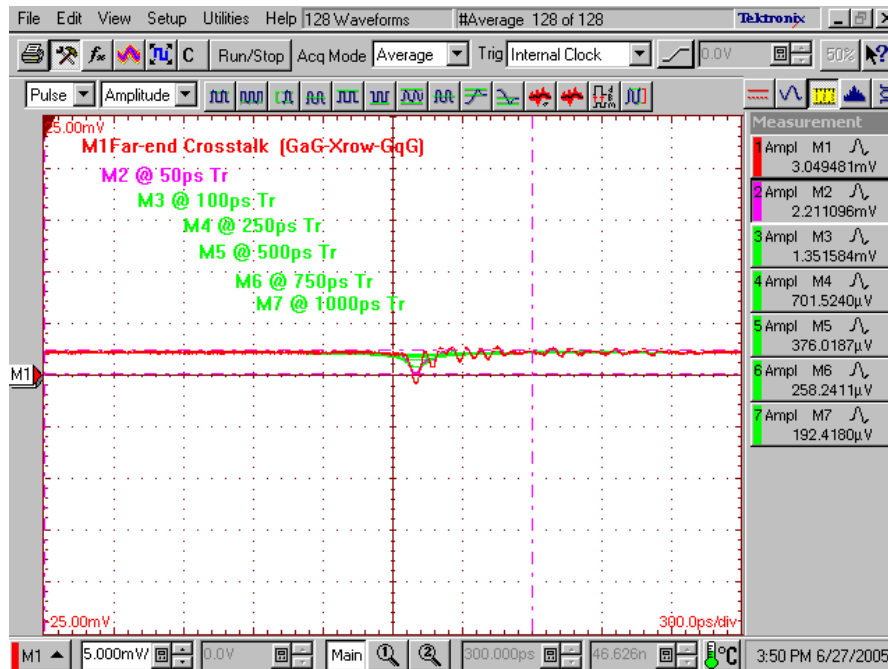
Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Single-Ended Application – NEXT, Across Row



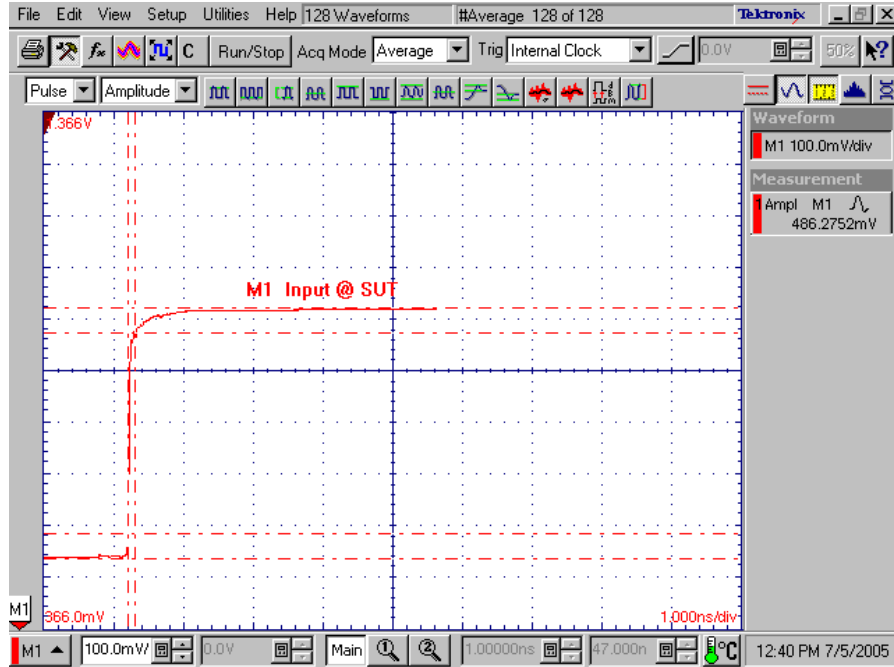
Single-Ended Application – FEXT, Across Row



Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

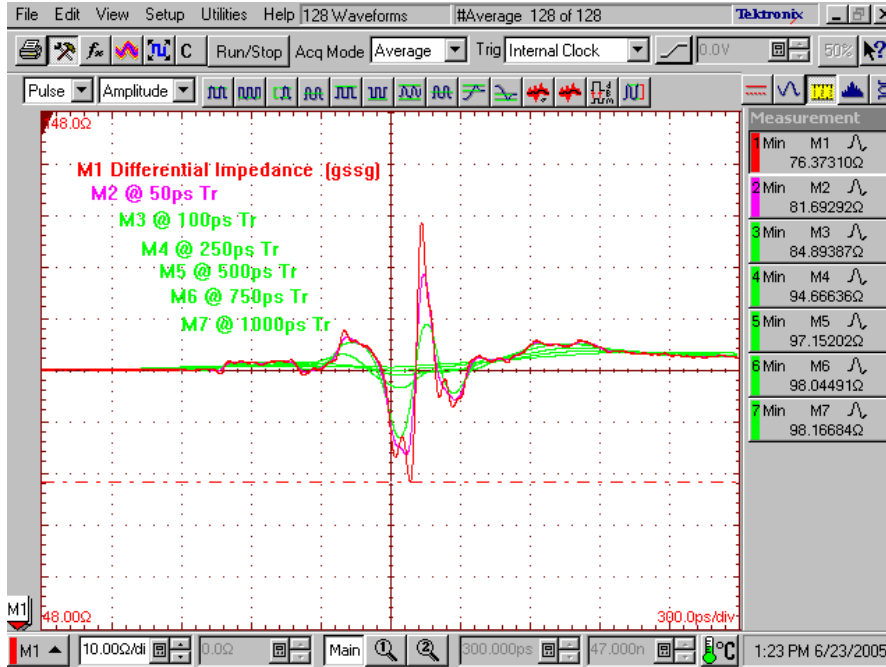
Differential Application – Input Pulse



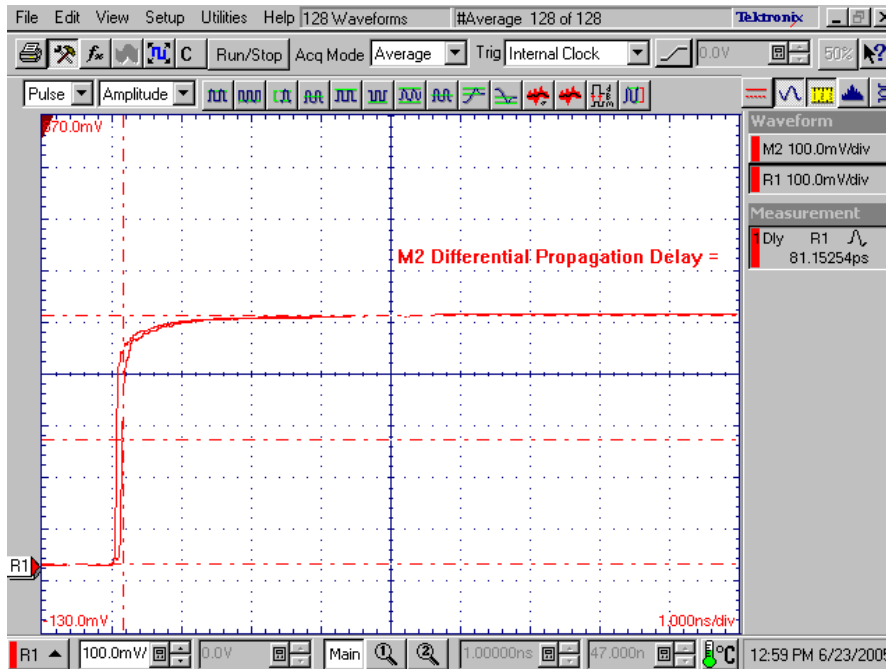
Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Differential Application – Impedance



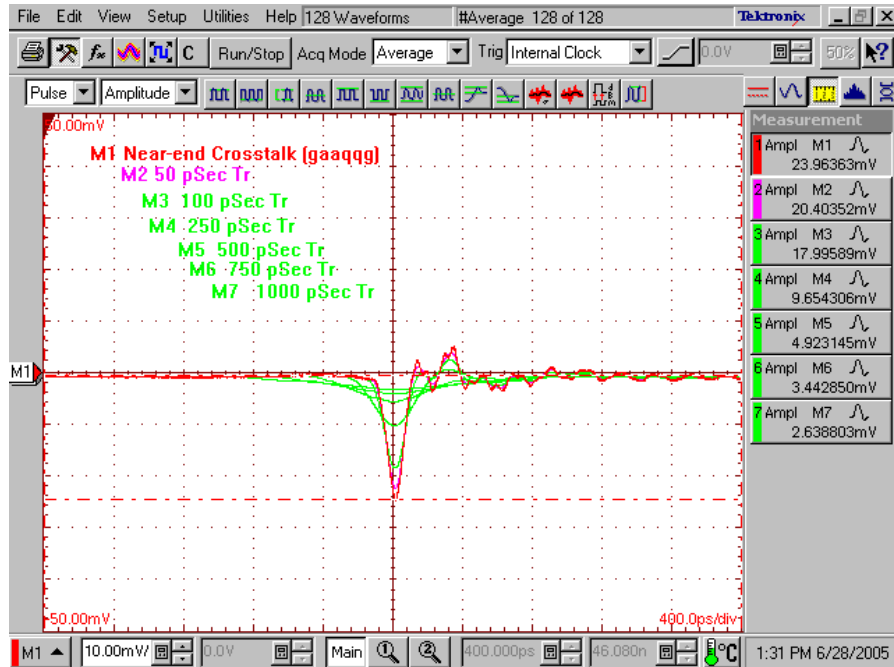
Differential Application – Propagation Delay



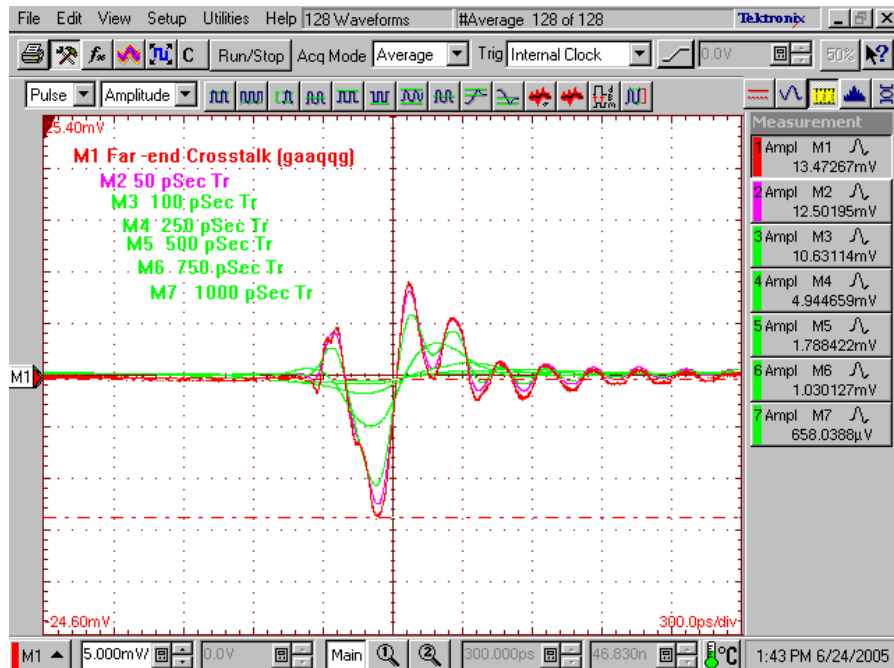
Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Differential Application – NEXT, “Worst Case” Configuration



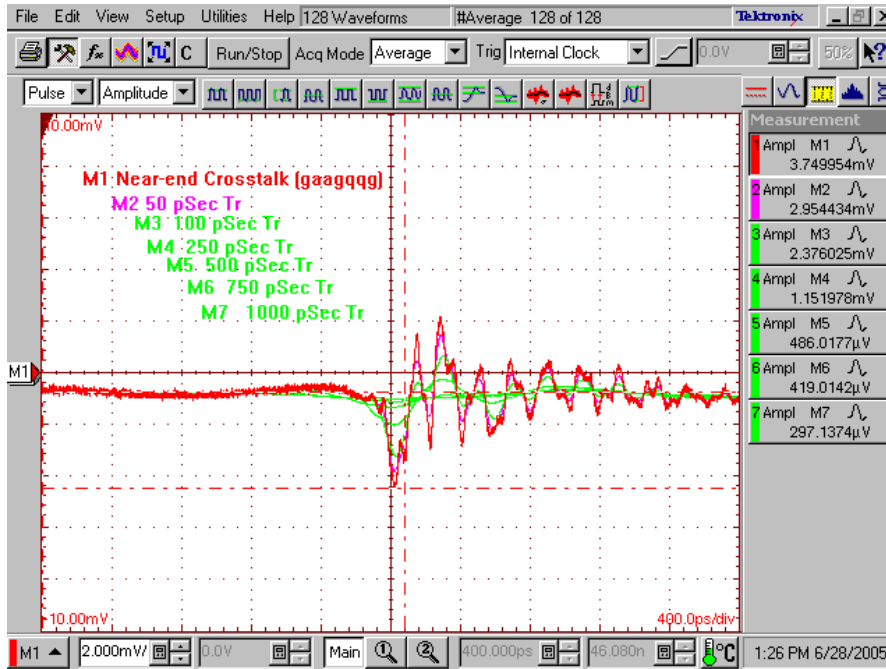
Differential Application – FEXT, “Worst Case” Configuration



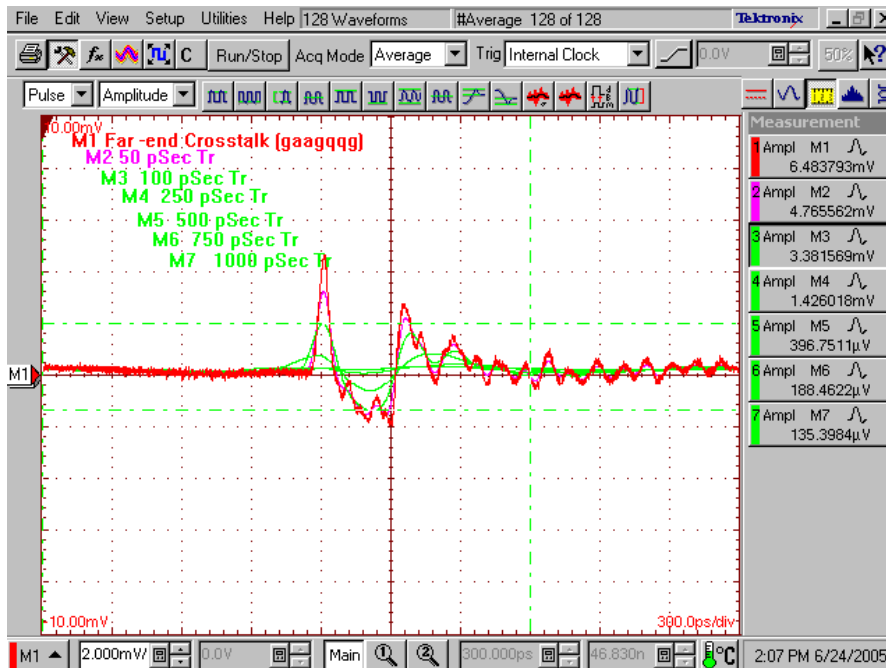
Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Differential Application – NEXT, “Best Case” Configuration



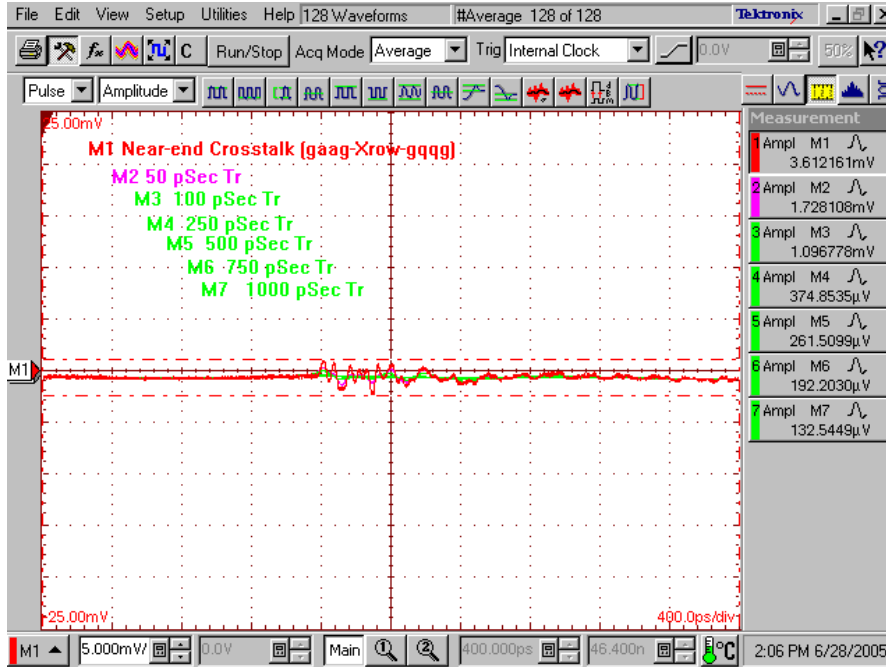
Differential Application – FEXT, “Best Case” Configuration



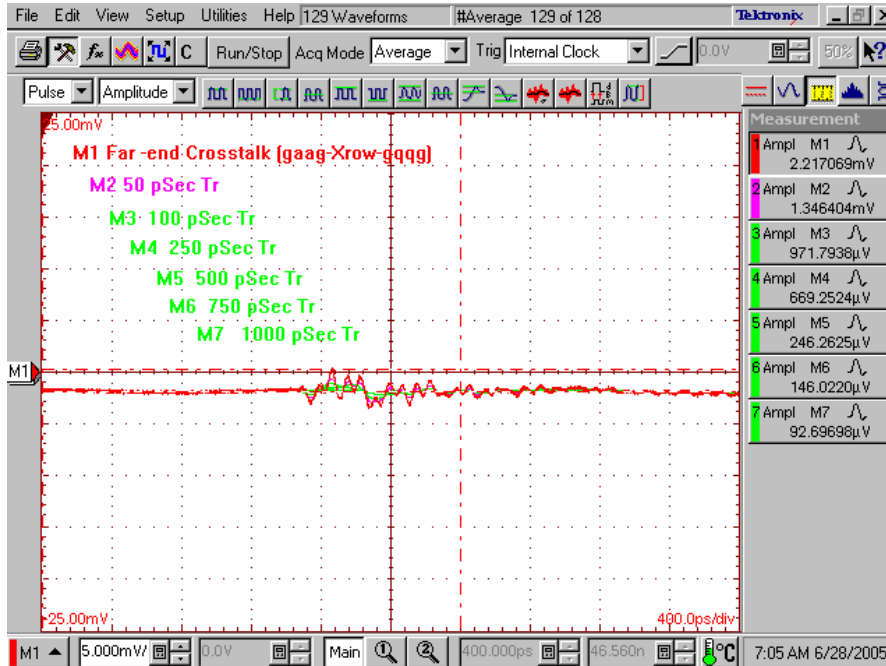
Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Differential Application – NEXT, Across Row



Differential Application – FEXT, Across Row



Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Appendix C – Product and Test System Descriptions

Product Description

Product samples are the basic socket BSE-040-01-F-D-A and basic terminal BTE-040-01-F-D-A strip connectors. Upon mating a standard board-to-board stack height of 5mm (0.197") exists between boards

Each connector structure consists of 2 rows of 40 positions mounted into a plastic housing with a surface mount design. The contacts are evenly spaced at a .8mm (.0315") pitch

Test System Description

The test fixtures are composed of a 4-layer FR-4 material with 50Ω and 100Ω signal trace and pad configurations designed for the electrical characterization of Samtec high-speed connector products. The pictured fixtures are specific to the BSE/BTE series connector and are identified by Samtec P/N PCB-100260-TST-01 and P/N PCB-100260-TST-02 (Figure 1)

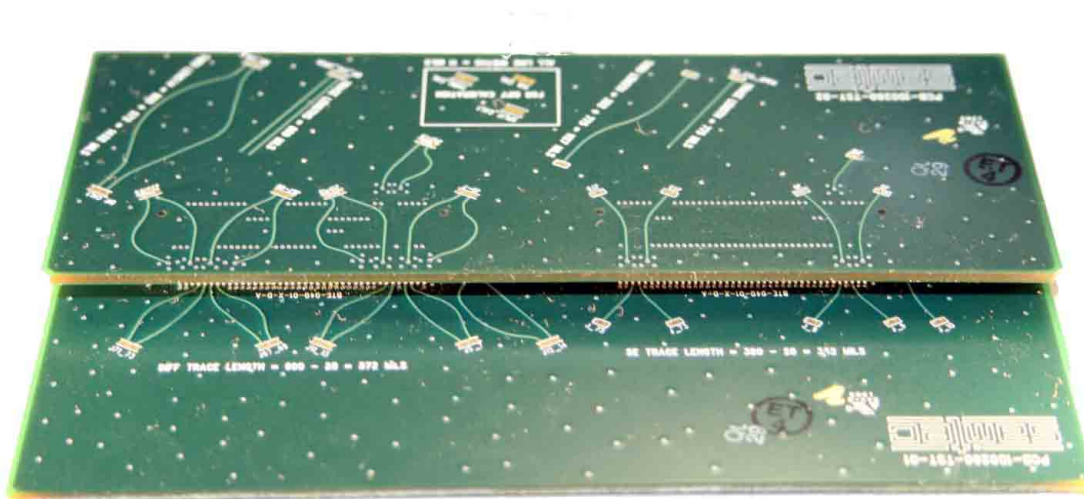


Figure 1 Mated PCB Test Fixture with Mounted Test Connectors

PCB-100260-TST-02 (Figure 1, top pcb) is designated for test signal launch and mounts two BSE-040-01 socket series connectors. The connector with single signal traces and probe pads (GSG) is for characterizing single ended test signals. The connector with paired signal traces is for characterization of differential test signals(GSSG). PCB-100260-TST-02 also provides the reference plane and/or calibration standards for gen-

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

erating time delay and s-parameter information. Terminated to PCB-100260-TST-01 are two BTE-040-01 terminal connectors (Figure 1, bottom PCB). When the two board fixtures are mated the identified probe points coordinate to create continuous electrical transmission paths between the signal launch pads and monitoring junctions. Both the single-ended and differential fixtures “J” number represents each terminal’s designated position within the connector. Signals can be launched or received from either the socket or header side of the connector. All data and waveforms presented in the report are results from a socket side signal launch. Table 8 below identifies the launch, monitoring and adjacent line termination points used in generating characterization test parameters contained in this report.

Table 8 – PCB Fixture Characterization Setup

	Single Ended				Differential			
	Launch	Monitor	50Ω to Gnd. Termination		Launch	Monitor	100Ω across Sig. Pair Termination	
USE PCB	TST-02	TST-01	TST-01	TST-02	TST-02	TST-01	TST-01	TST-02
IL, RL Z, PD	J5	J5	J9 J10	J9 J10	J5-7	J5-7	J11-13 J12-14	J11-13 J12-14
USE PCB	TST-02	TST-02	TST-01	TST-02	TST-02	TST-02	TST-01	TST-02
NEXT (worst)	J73	J75	J73 J75		J67-69	J71-73	J67-69 J71-73	
NEXT (best)	J5	J9	J5,J9, J10	J10	J5-7	J11-13	J5-7, J11-13, J12-14	J12-14
NEXT (xrow)	J5	J10	J5,J9, J10	J9	J5-7	J12-14	J5-7, J11-13, J12-14	J11-13
USE PCB	TST-02	TST-01	TST-01	TST-02	TST-02	TST-01	TST-01	TST-02
FEXT (worst)	J73	J75	J73	J75	J67-69	J71-73	J67-69	J71-73
FEXT (best)	J5	J9	J5 J10	J9	J5-7	J11-13	J5-7, J12-14	J11-13 J12-14
FEXT (xrow)	J5	J10	J5 J9	J9 J10	J5-7	J12-14	J5-7, J11-13	J11-13 J12-14

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Appendix D – Test and Measurement Setup

Test instruments are a Tektronix CSA8000 Communication Signal Analyzer Mainframe and the Agilent 8720ES Vector Network Analyzer. Four bays of the CSA8000 are occupied with three Tektronix 80E04 TDR/Sampling Heads and one Tektronix 80E03 Sampling Head. For this series of tests, four of the eight TDR/Sampling Head capability is used (*Figure 2*). The 8720ES serves as a supporting test instrument for verification or troubleshooting results obtained from the TDA Systems IConnect Software package. IConnect is a TDR based measurement software tool used in generating frequency domain related responses from high speed interconnects.

The probe stations illuminated video microscopy system, microprobe positioners, and 40GHz capable probes provide both the mechanical properties and electrical characteristics for obtaining the precise signal launch and calibrations that are critical in obtaining accurate high speed measurements. The 450 micron pitch probes are located to PCB launch points with 25X to 175X magnification and XYZ fine positioning adjustments available from both the probe table and micro-probe positioners. Electrically the micro-wave probes rate a < 1.0 dB insertion loss, a < 18 dB return loss, and an isolation of 38 dB to 40 GHz (*Figure 3*). Test cables and interconnect adapters are high quality and insure high-bandwidth and low parasitic measurements.

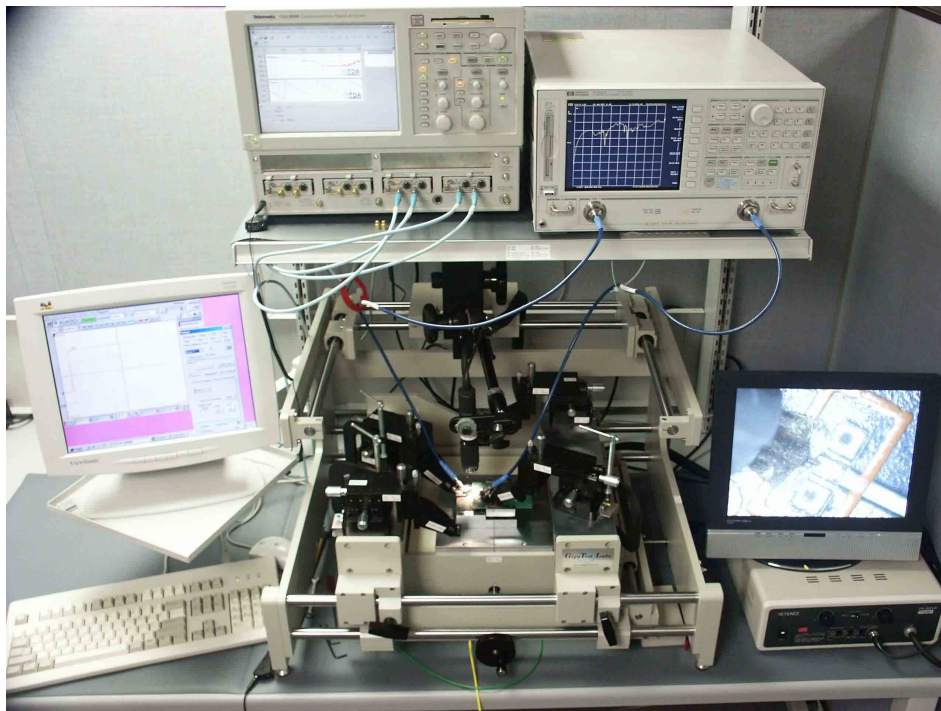


Figure 2 – Probe Station Measurements Capability

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Test Instruments

<u>QTY</u>	<u>Description</u>
1	Tektronix CSA8000 Communication Signal Analyzer
3	Tektronix 80E04 Dual Channel 20 GHz TDR Sampling Module
1	Tektronix 80E03 Dual Channel 20 GHz Sampling Module
1	Agilent 8720ES Vector Network Analyzer, 50 MHz to 20 GHz

Measurement Station Accessories

<u>QTY</u>	<u>Description</u>
1	GigaTest Labs Model (GTL3030) Probe Station
4	GTL Micro-Probe Positioners
2	Picoprobe by GGB Ind. Model 40A GSG (single ended applications)
2	Picoprobe by GGB Ind. Dual Model 40A GSG-GSG (differential applications)
1	Keyence VH-5910 High Resolution Video Microscope
1	Keyence VH-W100 Fixed Magnification Lens 100 X
1	Keyence VH-Z25 Standard Zoom Lens 25X-175X
1	CS-9 GSG Picoprobe Calibration Substrate (U9450.sq)
1	CS-11 GS-SG Picoprobe Calibration Substrate (U11450.sq)

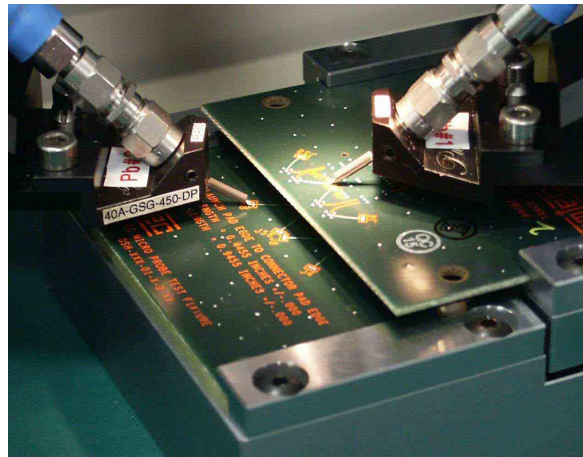


Figure 3 – 40 GHz High Performance Microwave Probes

Test Cables & Adapters

<u>QTY</u>	<u>Description</u>
4	Micro-Coax Cable Assembly 48" 3.5mm Male to 3.5mm Female, 26.5 GHz (IL = .33 dB@ 10 GHz)
2	Huber-Suhner Cable Assembly 36" SMA Female to SMA Female 26.5 GHz (IL = .34 dB @ 10 GHz)
4	Pasternack Precision Adapters, 3.5 mm Male to 2.9(K) Male, Max.VSWR 1.25 @ 34GHz

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Appendix E - Frequency and Time Domain Measurements

It is important to note before gathering measurement data that TDA Systems IConnect measurements and CSA8000 measurements are virtually the same measurements with diverse formats. This means that the operator, being extremely aware, can obtain SI time and frequency characteristics in an almost simultaneous fashion.

Since IConnect setup procedures are specific to the frequency information sought, it is mandatory that the sample preparation and CSA8000 functional setups be consistent throughout the waveform gathering process. If the operators test equipment permits recall sequencing between the various test parameter setups, it insures IConnect functional setups remain consistent with the TDR/TDT waveforms previously recorded. Related time and frequency test parameter data recorded for this report were gathered simultaneously.

Frequency (S-Parameter) Domain Procedures

Frequency data extraction involves two steps that first measure the frequency related time domain waveform followed by post-processing of the time domain waveforms into loss and crosstalk response parameters versus frequency. The first step utilizes the Tektronix CSA8000 time based instrument to capture frequency related single-ended or differential signal types propagating through an appropriately prepared SUT. The second step involves a correlation of the time based waveforms using the TDA Systems IConnect software tool to post-process these waveforms into frequency response parameters. TDA Systems labels these frequency related waveform relationships as the *Step* and *DUT* reference. This report establishes the setup procedures for defining the *Step* and *DUT* reference for frequency parameters of interest. Once established, the *Step* and *DUT* references are post-processed in IConnect's S-parameter computations window.

CSA8000 Setup

Listed below are the CSA 8000 functional menu setups used for single-ended and differential frequency response extractions. Both signal types utilize I-Connect software tools to generate S-parameter upper and lower frequency boundaries along with the step frequency. These frequency boundaries are determined by a time domain instruments functional settings such as window length, number of points and averaging capability. Once window length, number of points and averaging functions are set, maintain the same instrument settings throughout the extraction process.

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

	<u>Single-Ended Signal</u>	<u>Differential Signal</u>
Vertical Scale:	100 mV/ Div:	100 mV/ Div:
Offset:	Default / Scroll	Default / Scroll
Horizontal Scale:	1nSec/ Div = 20 MHz step frequency	1nSec/ Div = 20 MHz step frequency
Max. Record Length:	4000 = Min. Resolution	4000 = Min. Resolution
Averages:	≥ 128	≥ 128

Insertion Loss

SUT Preparation – Use path J5 to J5 for through measurements and J5_7 to J5_7 for differential through measurements. Adjacent inactive transmission paths are terminated 50Ω to GND single-ended or 100Ω differentially (*reference Table 8 Fixture Characterization Setup for test probe pad terminations*).

Step Reference - Establish this waveform by making a TDT transmission measurement that includes all cables, adapters, and probes connected in the test systems transmission path. A transmission path can be completed by inserting a negligible length of transmission standard between the microwave probes. (**Note:** Use *split-cal1 standard located on Samtec PCB100260-TST-02 fixture*).

DUT Reference - Establish this waveform by making an active TDT transmission measurement that includes all cables, adapters, and probes connected in the test systems transmission path. Insert the SUT between the probes in place of the transmission standard *and record* measurement

Return Loss

SUT Preparation – – Use J5 to J5 as the single ended impedance matched path and J5_7 to J5_7 as the differential impedance matched path. Adjacent inactive transmission paths are terminated 50Ω to GND single-ended or 100Ω differentially (*reference Table 8 Fixture Characterization Setup for test probe pad terminations*).

Step Reference - Establish the waveform by making an active TDR reflection measurement that includes all cables, adapters, and probes connected in the test systems electrical path up to and including an open standard. (**Note:** Use *split-cal1 standard located on Samtec PCB100260-TST-02 fixture*).

DUT Reference - Establish the waveform by making a TDT (matched) reflection measurement that includes all cables, adapters, and probes connected in the test systems transmission path. Cables and adapters located on the far-end of the inserted SUT provide the resistive load impedance that closely matches the test systems input impedance condition of 50Ω single-ended or 100Ω differential.

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Near-End Crosstalk (NEXT)

SUT Preparation – Launch single ended signals at J5 and differential signals at J5_7 probe pads of the PCB100260-02 fixture. Monitor signals at the designated worst, best, and across row probe pad of TST-01 or TST-02 board. Reference “Table 8 - Fixture Characterization Setup” for launch, monitoring and termination criteria.

Step Reference - Establish this waveform by making an active measurement that includes all cables, adapters, and probes connected in the test systems electrical path up to and including an open standard. (**Note:** Use *split-cal1* standard located on Samtec PCB100260-TST-02 fixture)

DUT Reference - Establish these waveforms by driving an active signal line (i.e.; J5) and recording the TDR coupled energy at the adjacent near-end (i.e.; J9). Repeat measurement procedures to establish the waveforms for worse case and across row (xrow) coupling conditions for both signal types. Reference “Table 8 - Fixture Characterization Setup” for launch, monitoring and termination criteria.

Far-End Crosstalk (FEXT)

SUT Preparation - Launch single ended signals at J5 and differential signals at J5_7 probe pads of the PCB100260-02 fixture. Monitor signals at the designated worst, best, and across row probe pad of TST-01 or TST-02 board. Reference “Table 8 - Fixture Characterization Setup” for launch, monitoring and termination criteria.

Step Reference - Establish this waveform by making a TDT transmission measurement that includes all cables, adapters, and probes connected in the test systems transmission path. The transmission path is completed by inserting a negligible length of transmission standard (**Note:** Use *split-cal1* standard located on Samtec PCB100260-TST-02 fixture).

DUT Reference - Establish these waveforms by driving an active signal line (i.e.; J5) and recording the TDR coupled energy at the adjacent far-end (i.e., J9). Repeat procedures to establish the waveforms for worse case and across row coupling conditions for both signal types. . Reference “Table 8 - Fixture Characterization Setup” for launch, monitoring and termination criteria.

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Time Domain Procedures

Measurements involving digital type pulses are performed utilizing either Time Domain Reflectometer (TDR) or Time Domain Transmission (TDT) methods. For this series of tests, TDR methods are employed for the impedance and propagation delay measurements. Crosstalk measurements utilize TDT methods. The Tektronix 80E04 TDR/ Sampling Head provide both the signaling type and sampling capability necessary to accurately and fully characterize the SUT.

Impedance

The signal line(s) of the SUT's signal configuration is energized with a TDR pulse. The far-end of the energized signal line is terminated in the test systems characteristic impedance (e.g.; 50 Ω or 100 Ω terminations). By terminating the adjacent signal lines in the test systems characteristic impedance, the effects on the resultant impedance shape of the waveform is limited. Reference "Table 8 - Fixture Characterization Setup" for launch, monitoring and termination criteria.

Propagation Delay

This connector series uses the fastest edge rate (30ps) of the TDR impedance waveform to measure propagation delay. . Differential or single ended signal delay is the measured difference of propagation between the known signal trace length delay (*reference PCB100260-TST-02 thru lengths 1127 mils for single ended & 1432 mils for differential propagation delay measurements*) and the delay of a mated SUT. The measurement is a one-way propagation result. Termination of the adjacent signal lines into the test systems characteristic impedance eliminate alternate current paths providing for better measurement accuracy. Reference "Table 8 - Fixture Characterization Setup" for launch, monitoring and termination criteria.

Crosstalk

An active pulsed waveform is transmitted through a selected SUT signal line. The adjacent quiet signal lines are monitored for the coupled energy at the near-end and far-end. Active and quiet lines not being monitored are terminated in the test systems characteristic impedance. Signal lines adjacent to the quiet lines remain terminated on both ends throughout the test sequence. Failing to terminate the active near or far end, quiet lines, or in some cases, signal lines adjacent to the quiet line may have an effect on amplitude and shape of the coupled energy. Reference "Table 8 - Fixture Characterization Setup" for launch, monitoring and termination criteria.

Series: BSE/BTE

Description: Parallel Board-to-Board, 0.8mm Pitch, 5mm (0.197") Stack Height

Appendix F – Glossary of Terms

BC – Best Case crosstalk configuration

DP – Differential Pair signal configuration

DUT – Device under test; TDA IConnect reference waveform

FEXT – Far-End Crosstalk

GSG – Ground–Signal–Ground; geometric configuration

NEXT – Near-End Crosstalk

PCB – Printed Circuit Board

SE – Single-Ended

SI – Signal Integrity

SUT – System under test

TDR – Time Domain Reflectometry

TDT – Time Domain Transmission

WC – Worse Case crosstalk configuration

Xrow^{se} – Cross ground/ power bar crosstalk, single-ended signal

Xrow^{diff} – Cross ground/ power bar crosstalk, differential signal

Z – Impedance (expressed in ohms)